

PRELIMINARY AMENDMENT
Divisional of USAN 09/793,108

Q76625

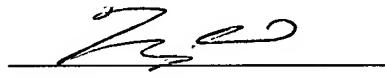
REMARKS

In this Preliminary Amendment, claim 8 has been added as a new claim. Support for this new claim can be found in the specification at, for example, pages 14 to 15, and original claims 1 and 6.

Claims 1-7 have been cancelled.

No new matter has been added. Entry and consideration of this Amendment are respectfully requested.

Respectfully submitted,



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APPENDIX

VERSION WITH MARKINGS TO SHOW CHANGES MADE

IN THE CLAIMS:

Claims 1-7 are canceled.

Please add the following new claims:

8. (New) A method for processing a semiconductor wafer comprising the steps of:
adhering a pressure-sensitive adhesive sheet to a semiconductor wafer, the pressure-
sensitive adhesive sheet comprising a photo-transmitting base film, and a layer comprising an
ultraviolet-curable pressure-sensitive adhesive composition comprising a photoinitiator having a
molar absorptivity at 365 nm of at least 1,000 mol⁻¹·cm⁻¹ and a maximum absorption wavelength
of at least 420 nm;
exposing the pressure-sensitive adhesive sheet to an ultraviolet ray; and
peeling the pressure-sensitive adhesive sheet from the semiconductor wafer.